

METHODS AND SYSTEMS FOR FORMING SLOTS IN A
SEMICONDUCTOR SUBSTRATE

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ABSTRACT

The described embodiments relate to methods and systems of forming slots in a semiconductor substrate. In one exemplary embodiment, a slot is formed by cutting with a disk into a semiconductor substrate into one of a first and second surfaces. A trench is created in the semiconductor substrate into the other of the first and second surfaces to form in combination with said cutting a slot through the substrate.

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